

INTERNATIONAL STANDARD



**Printed boards design, manufacture and assembly – Vocabulary –
Part 2: Common usage in electronic technologies as well as printed board and
electronic assembly technologies**



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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.180; 31.190

ISBN 978-2-8322-5133-1

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS DESIGN, MANUFACTURE
AND ASSEMBLY – VOCABULARY –****Part 2: Common usage in electronic technologies as well
as printed board and electronic assembly technologies**

FOREWORD

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International Standard IEC 60194-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This first edition, together with IEC 60194-1, will cancel and replace IEC 60194:2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to IEC 60194:2015:

- a) exclusion of 32 general terms better served by other TCs;
- b) exclusion of 47 terms no longer used by the electronics assembly industry;
- c) inclusion of 13 new terms related with device embedded substrate technology;
- d) removal of identification codes for terms as well as annexes.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1442/CDV	91/1473/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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- withdrawn,
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PRINTED BOARDS DESIGN, MANUFACTURE AND ASSEMBLY – VOCABULARY –

Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies

1 Scope

This part of IEC 60194 covers terms and definitions related to printed board and electronic assembly technologies as well as other electronic technologies.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of electronics assembly technology, the terms and definitions in 3.1 to 3.24 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1 A

3.1.1

abrasive trimming

adjustment of the value of a film component by notching it with a finely adjusted stream of an abrasive material against the resistor surface

3.1.2

accelerated ageing

accelerated life test

test in which the parameters such as voltage and temperature are increased above normal operating values to obtain observable or measurable deterioration in a relatively short period of time

3.1.3

accelerated test

test to check the life expectancy of an electronic component or electronic assembly in a short period of time by applying a physically severe condition(s) to the unit under test

3.1.4

acceleration factor

AF

ratio of stress in reliability testing to the normal operating condition